



**Dual N-channel 20V, TSSOP-8 MOSFET 双 N-沟道场效应管**

**■ Features 特点**

Low on-resistance and maximum DC current capability 低导通电阻和最大直流电流能力

Super high density cell design 超高元胞密度设计

$R_{DS(ON)} \leq 25m\Omega @ V_{GS}=4.5V$

$R_{DS(ON)} \leq 40m\Omega @ V_{GS}=2.5V$

**■ Applications 应用**

Power Management in Note book 笔记本电源管理

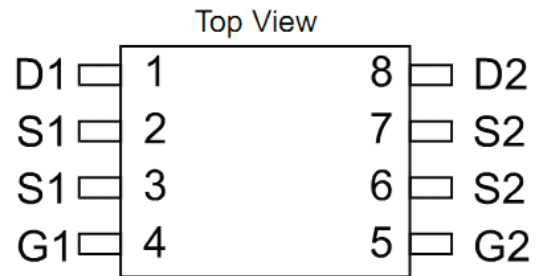
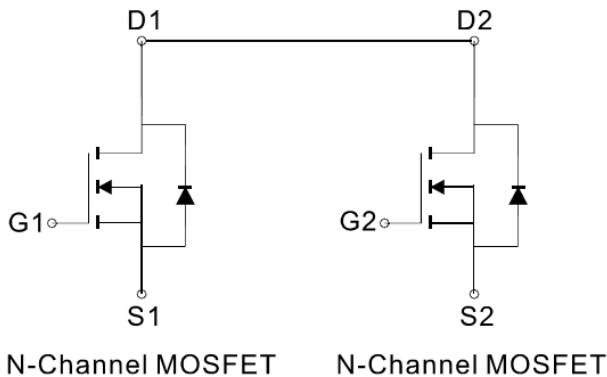
Portable Equipment 便携式设备

Battery Powered System 电池电源系统

DC/DC Converter 直流/直流变换

Load Switch 负载开关应用

**■ Internal Schematic Diagram 内部结构**



**■ Absolute Maximum Ratings 最大额定值**

Characteristic 特性参数	Symbol 符号	Max 最大值	Unit 单位
Drain-Source Voltage 漏极-源极电压	$BV_{DSS}$	20	V
Gate- Source Voltage 栅极-源极电压	$V_{GS}$	$\pm 8$	V
Drain Current (continuous) 漏极电流-连续	$I_D$	5.0	A
Drain Current (pulsed) 漏极电流-脉冲	$I_{DM}$	20	A
Total Device Dissipation 总耗散功率	$P_{TOT}$ (at $T_C = 25^\circ C$ ) (at $T_C = 70^\circ C$ )	2 1.6	W
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JA}$	78	$^\circ C/W$
Thermal Resistance Junction-Case 热阻	$R_{\theta JC}$	40	$^\circ C/W$
Junction/Storage Temperature 结温/储存温度	$T_J, T_{stg}$	-55~150	$^\circ C$

**Electrical Characteristics 電特性**

 (T<sub>A</sub>=25°C unless otherwise noted 如無特殊說明，溫度為25°C)

Characteristic 特性參數	Symbol 符號	Min 最小值	Typ 典型值	Max 最大值	Unit 單位
Drain-Source Breakdown Voltage 漏極-源極擊穿電壓(I <sub>D</sub> =250uA, V <sub>GS</sub> =0V)	BV <sub>DSS</sub>	20	—	—	V
Gate Threshold Voltage 柵極開啓電壓(I <sub>D</sub> =250uA, V <sub>GS</sub> =V <sub>DS</sub> )	V <sub>GS(th)</sub>	0.5	—	1.0	V
Zero Gate Voltage Drain Current 零柵壓漏極電流(V <sub>GS</sub> =0V, V <sub>DS</sub> =20V)	I <sub>DSS</sub>	—	—	1	uA
Gate Body Leakage 柵極漏電流(V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V)	I <sub>GSS</sub>	—	—	±100	nA
Static Drain-Source On-State Resistance 靜態漏源導通電阻(I <sub>D</sub> =7A, V <sub>GS</sub> =4.5V) (I <sub>D</sub> =6A, V <sub>GS</sub> =2.5V)	R <sub>DS(ON)</sub>	—	20 35	25 40	mΩ
Diode Forward Voltage Drop 內附二極管正向壓降(I <sub>SD</sub> =1.7A, V <sub>GS</sub> =0V)	V <sub>SD</sub>	—	—	1.2	V
Input Capacitance 輸入電容 (V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, f=1MHz)	C <sub>ISS</sub>	—	700	—	pF
Common Source Output Capacitance 共源輸出電容(V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, f=1MHz)	C <sub>OSS</sub>	—	175	—	pF
Reverse Transfer Capacitance 反向傳輸電容 (V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, f=1MHz)	C <sub>RSS</sub>	—	85	—	pF
Gate Source Charge 柵源電荷密度 (V <sub>DS</sub> =10V, I <sub>D</sub> =3A, V <sub>GS</sub> =4.5V)	Q <sub>gs</sub>	—	1.2	—	nC
Gate Drain Charge 柵漏電荷密度 (V <sub>DS</sub> =10V, I <sub>D</sub> =3A, V <sub>GS</sub> =4.5V)	Q <sub>gd</sub>	—	1.9	—	nC
Turn-On Delay Time 開啓延遲時間 (V <sub>DS</sub> =10V, I <sub>D</sub> =1A, R <sub>GEN</sub> =6Ω, V <sub>GS</sub> =4.5V)	t <sub>d(on)</sub>	—	8	—	ns
Turn-On Rise Time 開啓上升時間 (V <sub>DS</sub> =10V, I <sub>D</sub> =1A, R <sub>GEN</sub> =6Ω, V <sub>GS</sub> =4.5V)	t <sub>r</sub>	—	10	—	ns
Turn-Off Delay Time 關斷延遲時間 (V <sub>DS</sub> =10V, I <sub>D</sub> =1A, R <sub>GEN</sub> =6Ω, V <sub>GS</sub> =4.5V)	t <sub>d(off)</sub>	—	18	—	ns
Turn-On Fall Time 開啓下降時間 (V <sub>DS</sub> =10V, I <sub>D</sub> =1A, R <sub>GEN</sub> =6Ω, V <sub>GS</sub> =4.5V)	t <sub>f</sub>	—	5	—	ns



■ TYPICAL CHARACTERISTIC CURVE  
典型特性曲线

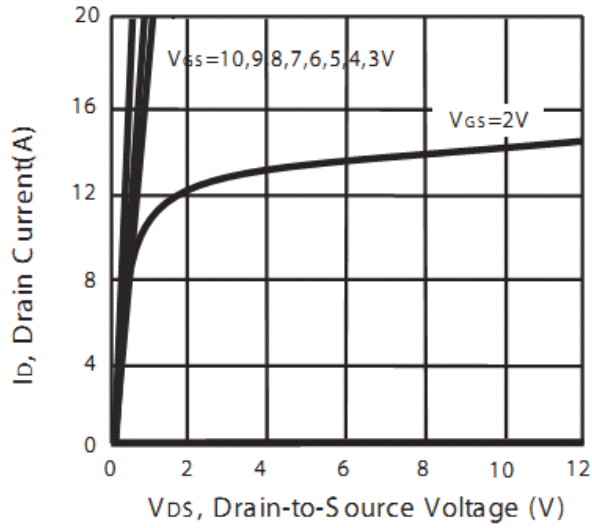


Figure 1. Output Characteristics

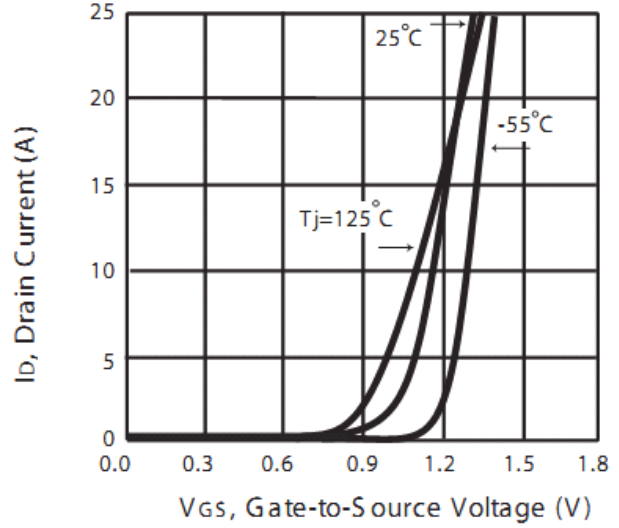


Figure 2. Transfer Characteristics

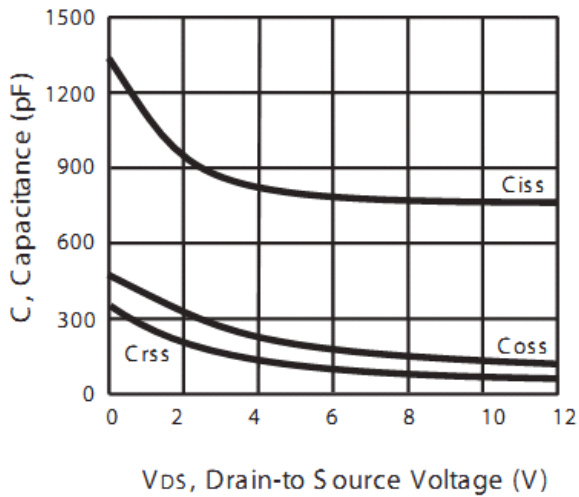


Figure 3. Capacitance

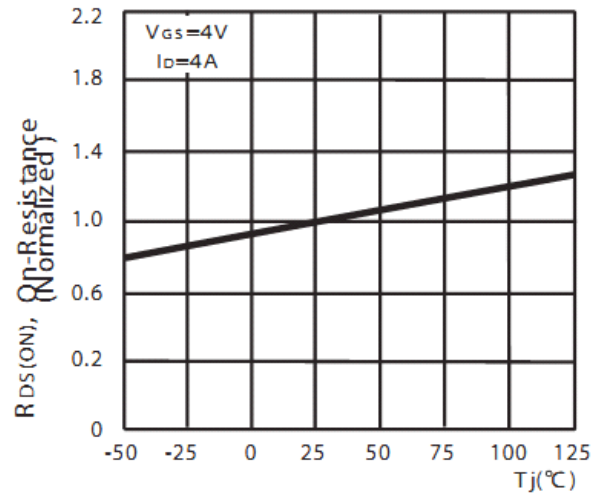
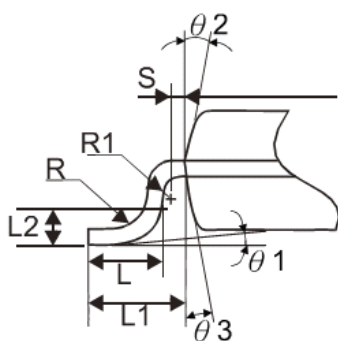
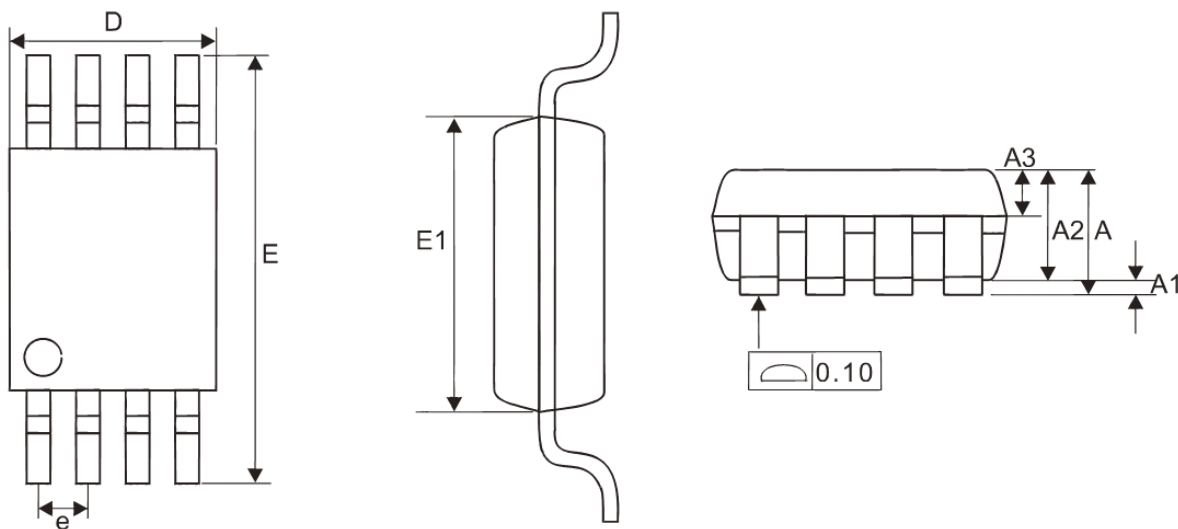


Figure 4. On-Resistance Variation with Temperature

**■ DIMENSION 外形封装尺寸**


SYMBOL	MILLIMETERS	
	MIN	MAX
A	-	1.20
A1	0.05	0.15
A2	0.90	1.05
A3	0.34	0.54
D	2.90	3.10
E	6.20	6.60
E1	4.30	4.50
e	0.65BSC	
L	0.45	0.75
L1	1.00REF	
L2	0.25BSC	
R	0.09	-
R1	0.09	-
S	0.20	-
$\theta 1$	0°	8°
$\theta 2$	10°	14°
$\theta 3$	10°	14°

Note: 1. Refer to JEDEC MS-012AA.

2. Dimension "D" does not include mold flash, protrusions